

Description

The NTR2101PT1G uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

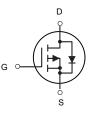
 V_{DS} = -20V, I_D = -5A RDS(ON) < 45m Ω @ VGS=4.5V

Application

High power and current handing capability Lead free product is acquired Surface mount package PWM applications Load switch Power management







P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
NTR2101PT1G	SOT-23	A5SHB XXXX	3000PCS

Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

Symbol	Parameter	Limit	Unit
VDS	Drain-Source Voltage	-20	V
Vgs	Gate-Source Voltage	±12	V
ID	Drain Current-Continuous	-5	А
Ідм	Drain Current-Pulsed (Note 1)	-14	А
PD	Maximum Power Dissipation	1.31	W
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C
Reja	Thermal Resistance, Junction-to-Ambient (Note 2)	120	°C/W



Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-20			V	
$\triangle BV_{\text{DSS}} / \triangle T_{\text{J}}$	BV _{DSS} Temperature Coefficient	Reference to 25° C , I _D =-1mA		-0.014		V/°C	
R _{DS(ON)}		V _{GS} =-4.5V , I _D =-4.9A		35	45	mΩ	
	Static Drain-Source On-Resistance ²	V _{GS} =-2.5V , I _D =-3.4A		45	60		
		V _{GS} =-1.8V , I _D =-2A		65	85		
V _{GS(th)}	Gate Threshold Voltage		-0.4		-1.0	V	
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} -V _{DS} ; I _D 2500A		3.95		mV/°C	
	Drain-Source Leakage Current	V_{DS} =-16V , V_{GS} =0V , T_{J} =25°C			-1	uA	
I _{DSS}	Drain-Source Leakage Current	V_{DS} =-16V , V_{GS} =0V , T_{J} =55°C			-5		
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 12V$, $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-3A		12.8		S	
Qg	Total Gate Charge (-4.5V)			10.2	14.3		
Q _{gs}	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-3A		1.89	2.6	nC	
Q _{gd}	Gate-Drain Charge			3.1	4.3		
T _{d(on)}	Turn-On Delay Time			5.6	11.2		
Tr	Rise Time	V_{DD} =-10V , V_{GS} =-4.5V ,		40.8	73		
T _{d(off)}	Turn-Off Delay Time	R _G =3.3Ω, I _D =-3A		33.6	67	ns	
T _f	Fall Time			18	36	1	
C _{iss}	Input Capacitance			857	1200		
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		114	160	pF	
C _{rss}	Reverse Transfer Capacitance			108	151		
Is	Continuous Source Current ^{1,4}				-4.9	А	
I _{SM}	Pulsed Source Current ^{2,4}	──V _G =V _D =0V , Force Current			-14	А	
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1	V	
t _{rr}	Reverse Recovery Time	IF=-3A,di/dt=100A/µs,		21.8		nS	
Q _{rr}	Reverse Recovery Charge			6.9		nC	

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

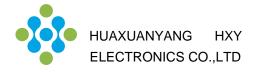
Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3.The power dissipation is limited by 150°C junction temperature

4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

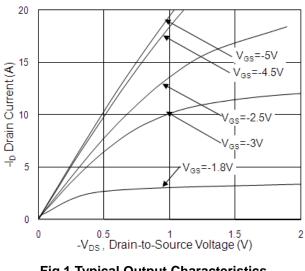


Fig.1 Typical Output Characteristics

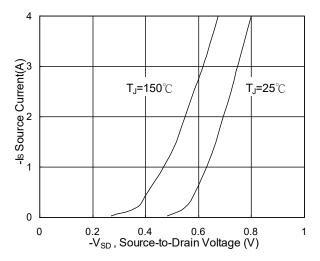


Fig.3 Forward Characteristics of Reverse

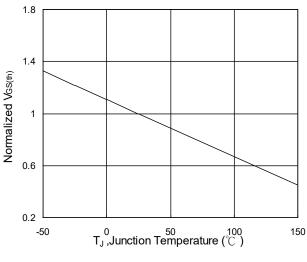


Fig.5 Normalized V_{GS(th)} vs. T_J

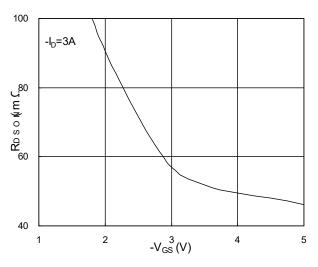


Fig.2 On-Resistance vs. G-S Voltage

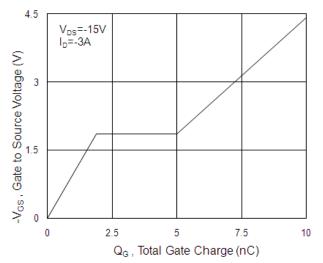


Fig.4 Gate-charge Characteristics

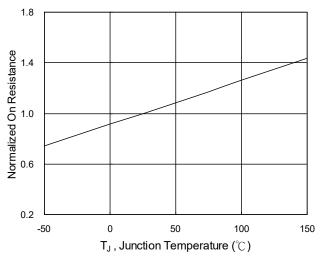
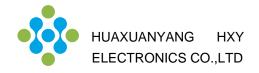
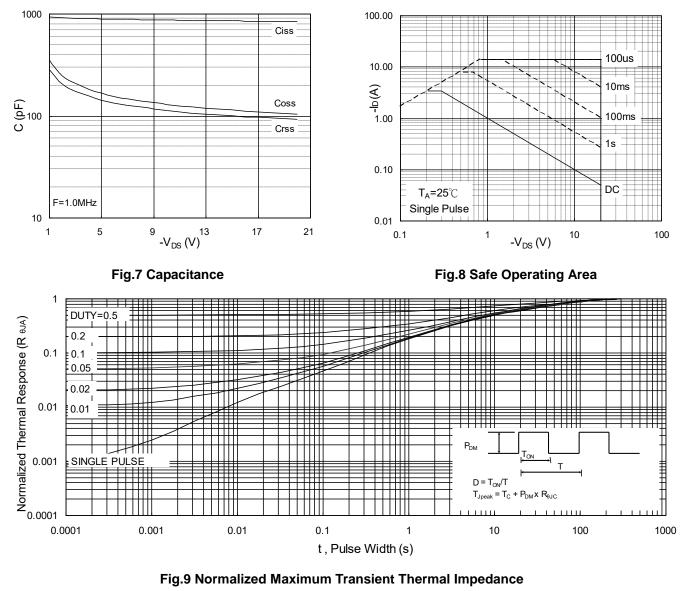


Fig.6 Normalized R_{DSON} vs. T_J





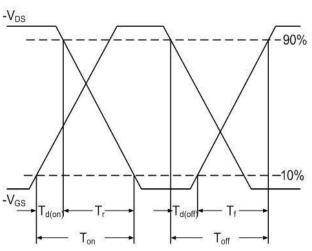


Fig.10 Switching Time Waveform

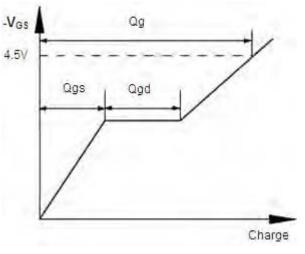
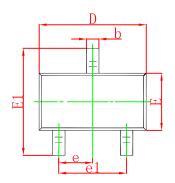
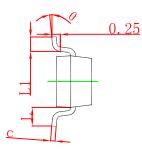


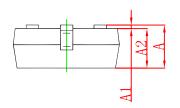
Fig.11 Gate Charge Waveform



SOT-23 Package Outline Dimensions

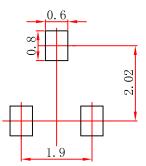






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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